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# **Schottky Diode**

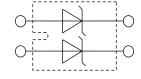
High Performance Schottky Diode Low Loss and Soft Recovery Parallel legs

Part number

Very low Vf

low Irm values

DSS2x101-015A



### Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

 $V_{RRM} = 150 V$   $I_{FAV} = 2x 100 A$   $V_{F} = 0.77 V$ 



Backside: isolated

**FL** E72873

#### Package:

- Housing: SOT-227B (minibloc)
- Industry standard outline
- Cu base plate internal DCB isolated
- Isolation Voltage 3000 V
- Epoxy meets UL 94V-0
- RoHS compliant

Improved thermal behaviour

• Extremely low switching losses

Features / Advantages:

- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- · Low noise switching

Ratings

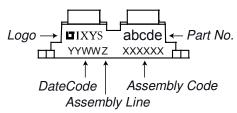
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V <sub>RRM</sub>	max. repetitive reverse voltage		T <sub>VJ</sub> = 25°C			150	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 150 V	$T_{VJ} = 25^{\circ}C$			4	mA
		$V_R = 150 V$	$T_{VJ} = 125$ °C			10	mΑ
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 100 A	$T_{VJ} = 25^{\circ}C$			0.91	V
		I <sub>F</sub> = 200 A				1.09	V
		I <sub>F</sub> = 100 A	T <sub>VJ</sub> = 125°C			0.77	V
		$I_F = 200 A$				0.99	V
I <sub>FAV</sub>	average forward current	rectangular d = 0.5	T <sub>C</sub> = 110°C			100	Α
V <sub>F0</sub>	threshold voltage slope resistance for power loss calculation only		T <sub>vJ</sub> = 150°C			0.53	V
r <sub>F</sub>						2.1	mΩ
R <sub>thJC</sub>	thermal resistance junction to case					0.40	K/W
T <sub>vJ</sub>	virtual junction temperature			-40		150	°C
P <sub>tot</sub>	total power dissipation		$T_{c} = 25^{\circ}C$			310	W
I <sub>FSM</sub>	max. forward surge current	t = 10 ms (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			1400	Α
C¹	junction capacitance	$V_R = 24 V$ ; $f = 1 MHz$	T <sub>VJ</sub> = 25°C		962		pF



Rating	S

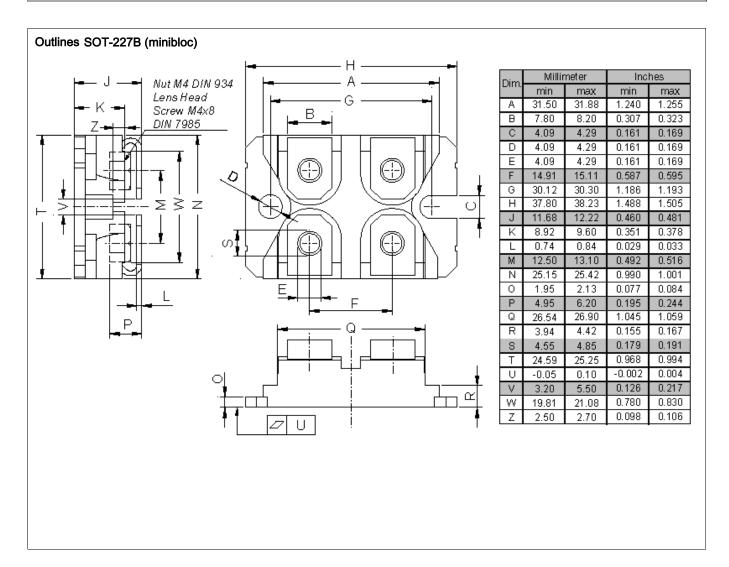
Symbol	Definition C	Conditions			min.	typ.	max.	Unit
I <sub>RMS</sub>	RMS current p	oer terminal					150	Α
RthCH	thermal resistance case to heatsink					0.10		K/W
T <sub>stg</sub>	storage temperature				-40		150	°C
Weight						30		g
M <sub>D</sub>	mounting torque				1.1		1.5	Nm
$M_{\tau}$	terminal torque				1.1		1.5	Nm
V <sub>ISOL</sub>	isolation voltage t	= 1 second			3000			V
	t	= 1 minute			2500			V
d <sub>Spp/App</sub>	creepage   striking distance on surface   thro	ough air	terminal to terminal	10.5	3.2			mm
d <sub>Spb/Apb</sub>	creepage   striking distance on surface   thro	ough air	terminal to backside	8.6	6.8			mm

### **Product Marking**

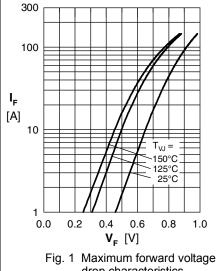


Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DSS2x101-015A	DSS2x101-015A	Tube	10	478474









drop characteristics

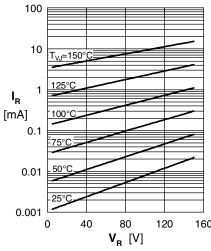


Fig. 2 Typ. reverse current  $I_R$  vs. reverse voltage  $V_R$ 

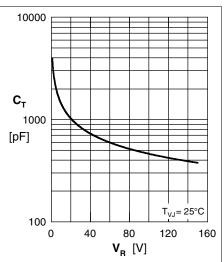


Fig. 3 Typ. junction capacitance  $C_T$  vs. reverse voltage  $V_R$ 

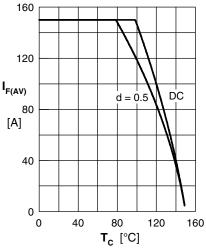


Fig. 4 Average forward current  $I_{F(AV)}$  vs. case temperature  $T_C$ 

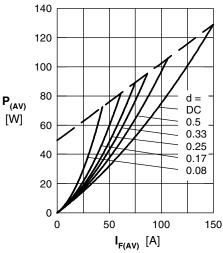


Fig. 5 Forward power loss characteristics

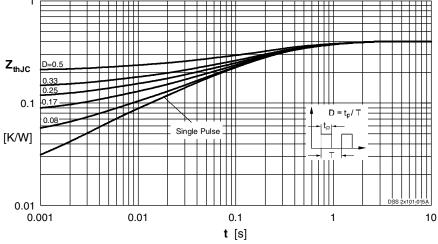


Fig. 6 Transient thermal impedance junction to case at various duty cycles

Note: All curves are per diode